

# IMBI-Q57

## Intel Q57 chipset Advance Mini-ITX Board Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input type="checkbox"/> <b>Pass with Deviation</b> Comment: _____				
	<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement	
Defect Found	0	0	0	1	
Defect Unsolved	0	0	0	1	

Issue date  
2010 / 09 / 07

Approval  
Jansin Lee

Test Engineer  
Allen Hsu

### Sample Configuration & Quantity Under Test

- **Model name : IMBI-Q57 Rev A0.2**
- **CPU Board: IMBI-Q57 Rev A0.2**
- **Carrier Board: N/A**
- **CPU: Intel Pentium CPU G6950 @2.80GHz / 32nm / QPI 2400MHz**
- **Memory: DSL DDR3 / 1066 / 2GB CL7 / ELPIDA J1108BABG-DJ-E  
DSL DDR3 / 1066 / 1GB CL7 / ELPIDA J1108BABG-DJ-E**
- **HDD: TOSHIBA 2.5" SATA H.D 160GB / MK1655GSX**
- **BIOS : IMBIQ57 1.00 09/03/2010**
- **Test Software: Windows XP sp3 / Run Prime95 v26.01**
- **ATX Power Supply: Delta ATX Power 350W GPS-350EB-102A**
- **Cooler:**



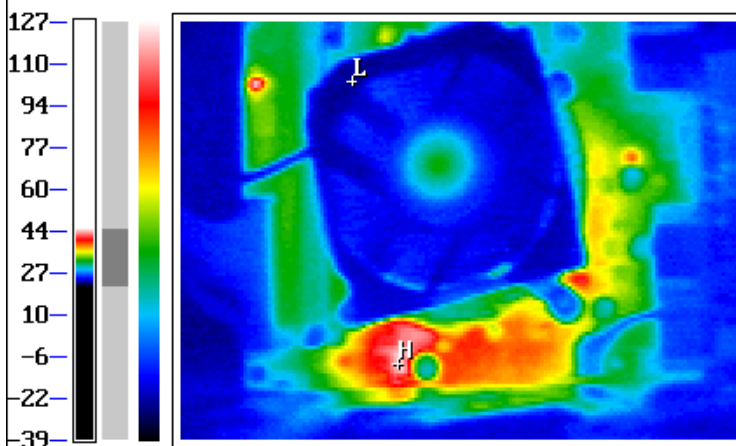
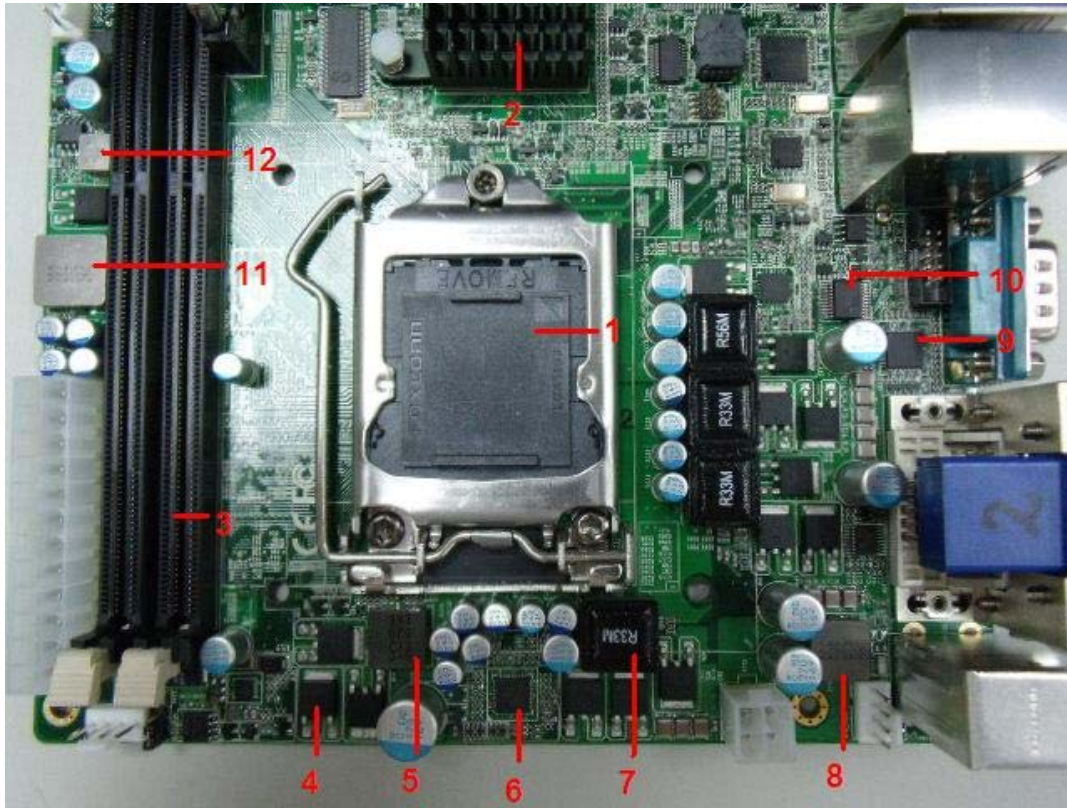
## Thermal Image Analysis

1. Test Date: 09/07/2010
2. Test Product: IMBI-Q57
3. Test Site: AAEON QA Internal Lab.
4. Temperature Measurement:
  1. GRAPHTEC midi LOGGER TYPE - GL200
  2. IR Scanner: Infrared Camera  
NIPPON AVIONICS CO., LTD.  
Model: TVS-100  
Date of Calibration: 09/17/09  
Serial Number: 0179L2746
5. Test Condition:  
Component Side-1 (Test by TVS-100 ): 25.2°C With cooler  
Component Side-2 (Test by TVS-100 ): 24.5°C With cooler  
Component Side-2 (Test by UR1000 ): 24.8°C With cooler
6. Test Software:  
Windows XP sp3 / Run Prime 95 v26.01
7. Take Picture Time:  
After power on 2 hours

### Temperature Profile Test:



Component Side-1:



COLOR ADJ.

AUTO ADJ.

U 44.4

D 21.6

HIGH(H) 42.71 X:124 Y:196

LOW(L) 23.06 X: 98 Y: 34

Emissivity:0.94

DATE : 2010/09/06

TIME : 14:27:19

Using GRAPHTEC midi LOGGER TYPE - GL200 test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.2°C	60°C	
1	CPU	Intel® Pentium® Processor G6950 (3M Cache, 2.80 GHz)	72.6	42.8	77.6	Defect NO. 1090912 QEE44
2	U13	(TF)IC.SMD.Chipset Ibex Peak PCH951P.INTEL.BD82Q57,SLGZW	111	41.2	76.0	
3	RAM	DSL DDR3 / 1066 / 2GB CL7 / ELPIDA J1108BABG-DJ-E	95	33.1	67.9	
4	Q11	(TF)PWR.SMD.TO-252.30V 94A.N-channel Power MOSFET.FAIRCHILD.FDD8896_NL;EE-A070814;13158896 12;TWN	150	36.0	70.8	
5	L7	(TF)COIL.0.15uH.Irms=40A.Isat=75A.20%.SMD(11.5x10.3x4.0)2pin.RDC=0.5.GOTREND.GSTC104P-R15MN	-----	38.5	73.3	
6	U12	(TF)IC.SMD.QFN 40Pin.VR11.1 4Phase PWM Controler.Intersil.ISL6334CRZ;EE-A090093;14S3633400;TWN	100	38.0	72.8	
7	L8	(TF)COIL.0.33uH.20%.DIP.40A.GOTREND.GMAT-131210-P-R33-M	-----	37.2	72.0	
8	L12	(TF)COIL.0.56uH.Irms=25A.Isat=40A.20%.SMD(11.5x10.3x4.0).2pin.RDC=1.8m Ohm.GOTREND.GSTC104P-R56MN;EE-A061714;1211105 673;TWN	125	33.4	68.2	
9	U29	(TF)IC.SMD.10P.Ultra Low Capacitance.TVS Arrays.SEMTECH.RClamp0524P.TCT;EE-A090136;14S30 52400;TWN	100	36.9	71.7	
10	U23	(TF)IC.SMD SSOP.20Pin RS-232 Driver&Receivers.TI.GD75232DBR;EE-A010945;14S5A23 200;TWN	100	35.9	70.7	
11	L1	(TF)COIL.2.2uH.SMD.13.8*12.8*5.0mm.DCR=4.6m ohm.Irms=20A.GOTREND.GSTC135P-2R2MF;EE-A07036 7;1211102266;TWN	125	35.7	70.5	
12	L2	(TF)COIL.1uH.+/-20%.SMD.7.3*6.8*3.0mm.DCR=9mohm.Irms=11Amp.GOTREND.GSTC063P-1R0MN;EE-A061520;1 211000180;TWN	125	37.8	72.6	

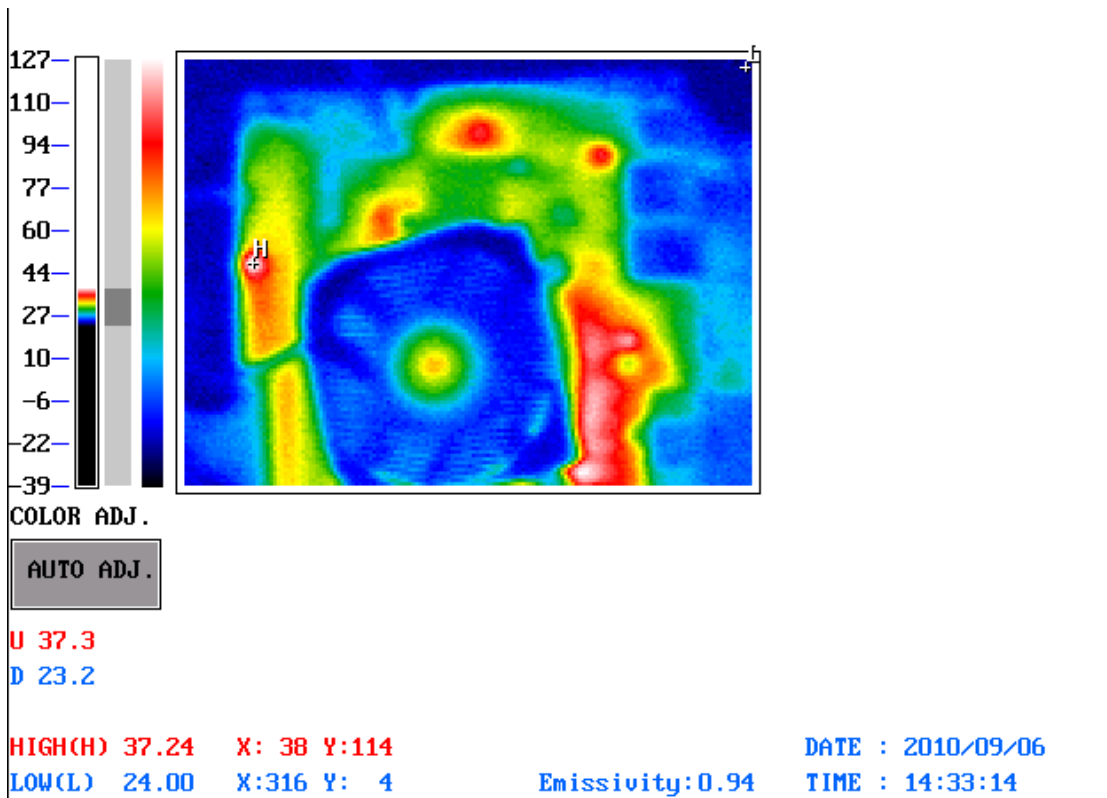
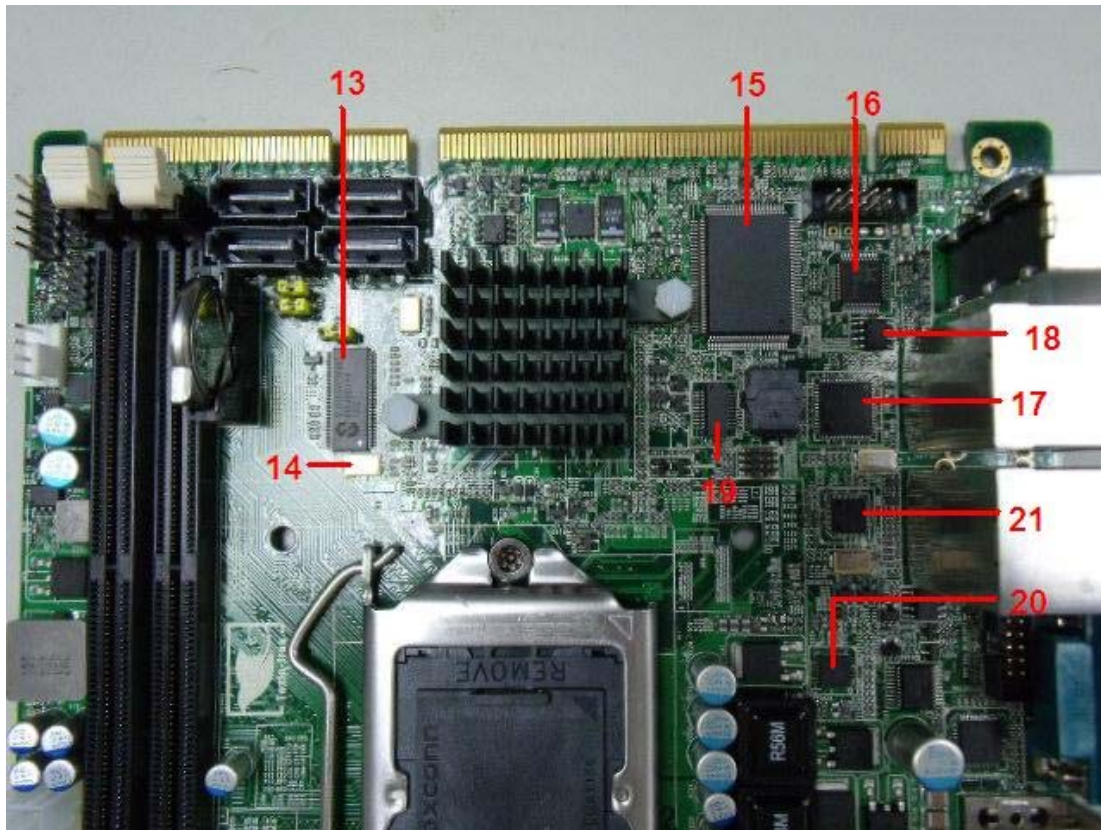
Note(\*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- Fail : Tm > Tc+5°C; The measured value is over specification plus margin.
- Margin : Tc+5 °C > Tm > Tc -10°C; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- Pass : Tm < Tc-10°C; The measured value is with safety margin.

Component Side-2:



Using GRAPHTEC midi LOGGER TYPE - GL200 test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				24.5°C	60°C	
13	U9	(TF)IC.SMD.TSSOP 64P.CLOCK GENERATOR.SILEGO.SLG505YC264BTTR;EE-A081678;14S3050500;TWN	100	32.3	67.8	
14	Y1	(TF)XTAL SMD.14.31818MHz.6*3.5 mm 20PPM.2P.仕野.XSX143180-S632-20;EE-A050533;123131435B;TWN	-----	34.9	70.4	
15	U15	(TF)IC.SMD.QFP128P Super I/O.ITE.IT8718F/HX-L;EE-A090544;14S4871800;TWN	100	42.1	77.6	
16	U19	(TF)IC.SMD.LQFP 48P.7.1Channel HD Audio Codec.REALTEK.ALC888-VC2-GR;EE-A081306;14S3088801;TWN	100	47.2	82.7	
17	U18	(TF)IC.SMD.QFN 64P.PCI-E GigaBit Ethernet Chipset.Intel.WG82574L SLBA8;EE-A081303;14S4825740;TWN	109	38.3	73.8	
18	U20	(TF)IC.SMD.SOIC.8P.8K SPI Bus Serial EEPROM.ATMEL.AT25080AN-10SU-2.7;EE-A061337;14S6308001;TWN	115	37.4	72.9	
19	U34	IDT/(TF)IC.SMD QSOP.20P.8 Bit Bus Switch.IDT.IDTQS3245QG;EE-A000251;14S5A24540;TWN	115	38.2	73.7	
20	U16	(TF)IC.SMD.QFN 32P.PWM Controller.INTERMIL.ISL6314CRZ-T	-----	37.2	72.7	
21	U17	(TF)IC.SMD.QFN 48P.PCI-E GigaBit Ethernet Chipset.Intel.WG82578DM SLGY6	85	35.9	71.4	

Note(\*):

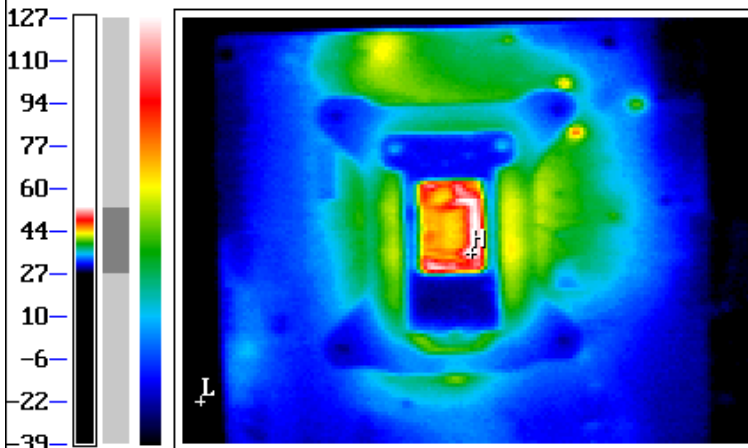
- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
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3. Judgment Criteria:

- **Fail** : Tm > Tc+5°C; The measured value is over specification plus margin.
- **Margin** : Tc+5°C > Tm > Tc-10°C; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : Tm < Tc-10°C; The measured value is with safety margin.



Component Side-3:



COLOR ADJ.

AUTO ADJ.

U 53.0

D 27.4

HIGH(H) 52.48 X:162 Y:132

LOW(L) 24.53 X: 10 Y:216

Emissivity:0.94

DATE : 2010/09/06

TIME : 14:38:18

Using GRAPHTEC midi LOGGER TYPE - GL200 test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				24..8°C	60°C	
22	U37	(TF)PNP.SMD.SC-62LowFrequencyTransistor.ROHM.2SB1386T100R;EE-A070393;1311138610;TWN	100	48.0	83.2	
23	U42	(TF)IC.SMD.SSOP RS232 Driver ESD15KV.AD.ADM213EARSZ;EE-A970562;14S4021301;TWN	115	40.8	76	
24	U40	(TF)IC.SMD.SOIC 8Pin.MOSFET Drivers.INTERASIL.ISL6612ACBZ;EE-A061931;14S9661200;TWN	115	53.5	88.7	
25	U44	(TF)IC.SMD.SO8.RS-485Transceiver.Analog.ADM485JRZ;EE-A050755;14S4048502;TWN	115	42.1	77.3	
26	U36	(TF)IC.SO8 SMD.Voltage Detecting.System Resetting IC.MITSUBISHI.M51957A;EE-A060753;14S4195710;TWN	----	46.1	81.3	
27	U32	(TF)REG.SMD SOP-8.2A Bus.Termination Regulator.RichTek.RT9173CPSP;EE-A071496;1314917314;TWN	95	37.4	72.6	

Note(\*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
- **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.